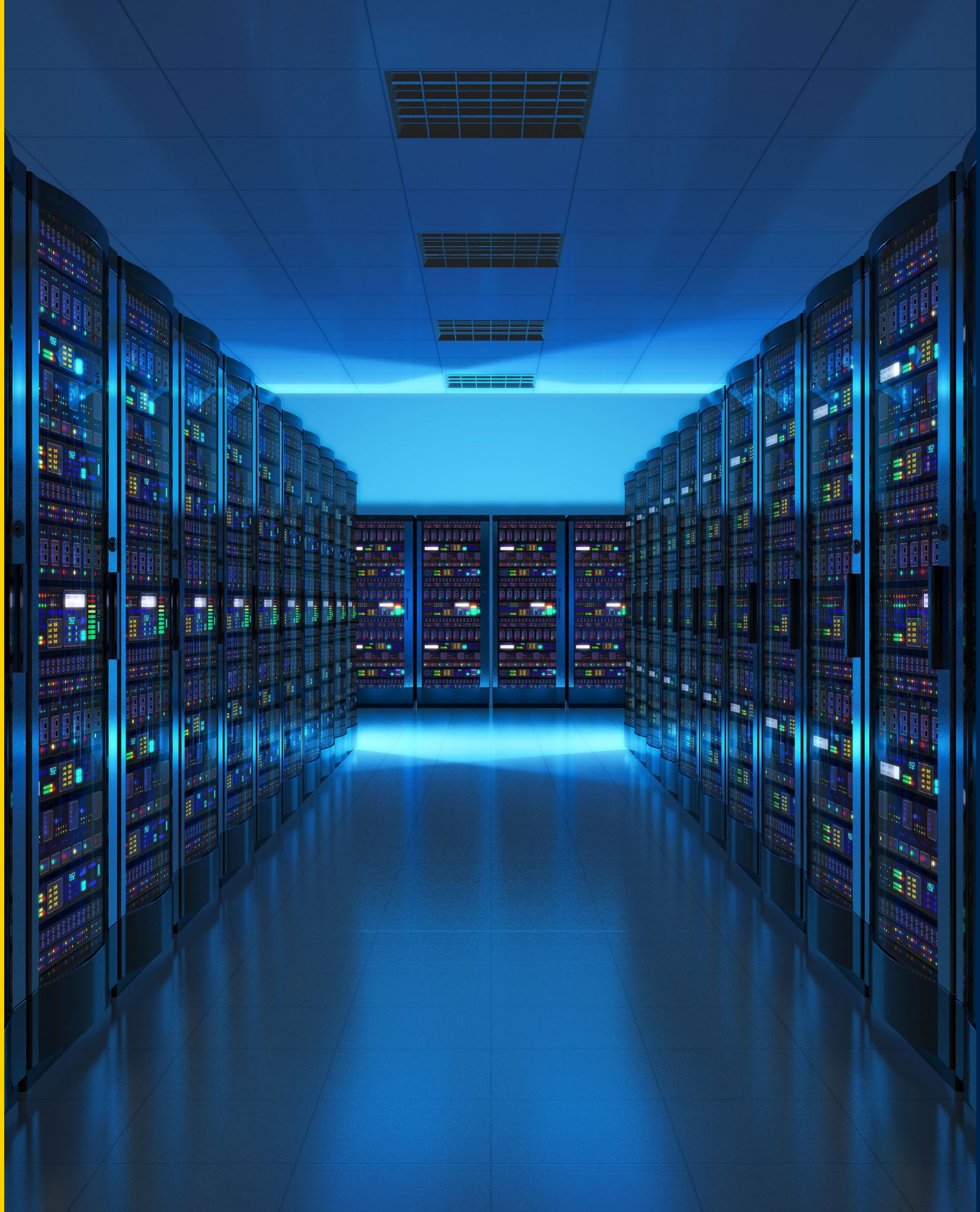


ST Cloud AI update

Remi El-Ouazzane

President, Microcontrollers, Digital ICs and RF products Group

March 9, 2026

Forward looking information

Some of the statements contained in this document that are not historical facts are statements of future expectations and other forward-looking statements (within the meaning of Section 27A of the Securities Act of 1933 or Section 21E of the Securities Exchange Act of 1934, each as amended) that are based on management's current views and assumptions, and are conditioned upon and also involve known and unknown risks and uncertainties that could cause actual results, performance or events to differ materially from those anticipated by such statements due to, among other factors:

- changes in global trade policies, including the continuation, adoption and expansion of tariffs and trade barriers and sanctions, that are affecting and could further affect the macro-economic environment and are adversely impacting and could further adversely impact the demand for our products;
- uncertain macro-economic and industry trends (such as inflation and fluctuations in supply chains), which are impacting and may further impact production capacity and end-market demand for our products;
- customer demand that differs from projections, which may require us to undertake transformation measures that may not be successful in realizing the expected benefits in full or at all;
- the ability to design, manufacture and sell innovative products in a rapidly changing technological environment;
- changes in economic, social, public health, labor, political, or infrastructure conditions in the locations where we, our customers, or our suppliers operate, including as a result of macro-economic or regional events, geopolitical and military conflicts, social unrest, labor actions, or terrorist activities;
- unanticipated events or circumstances, which may impact our ability to execute our plans and/or meet the objectives of our research and development ("R&D") and manufacturing programs, which benefit from public funding;
- financial difficulties with any of our major distributors or significant curtailment of purchases by key customers;
- the loading, product mix, and manufacturing performance of our production facilities and/or our required volume to fulfill capacity reserved with suppliers or third-party manufacturing providers;
- availability and costs of equipment, raw materials, utilities, third-party manufacturing services and technology, or other supplies required by our operations (including increasing costs resulting from inflation);
- the functionalities and performance of our IT systems, which are subject to cybersecurity threats and which support our critical operational activities including manufacturing, finance and sales, and any breaches of our IT systems or those of our customers, suppliers, partners and providers of third-party licensed technology;
- theft, loss, or misuse of personal data about our employees, customers, or other third parties, and breaches of data privacy legislation;
- the impact of intellectual property ("IP") claims by our competitors or other third parties, and our ability to obtain required licenses on reasonable terms and conditions;
- changes in our overall tax position as a result of changes in tax rules, new or revised legislation, the outcome of tax audits or changes in international tax treaties which may impact our results of operations as well as our ability to accurately estimate tax credits, benefits, deductions and provisions and to realize deferred tax assets;
- variations in the foreign exchange markets and, more particularly, the U.S. dollar exchange rate as compared to the Euro and the other major currencies we use for our operations;
- the outcome of ongoing litigation as well as the impact of any new litigation to which we may become a defendant;
- product liability or warranty claims, claims based on epidemic or delivery failure, or other claims relating to our products, or recalls by our customers for products containing our parts;
- natural events such as severe weather, earthquakes, tsunamis, volcano eruptions or other acts of nature, the effects of climate change, health risks and epidemics or pandemics in locations where we, our customers or our suppliers operate;
- increased regulation and initiatives in our industry, including those concerning climate change and sustainability matters and our goal to become carbon neutral in all direct and indirect emissions (scopes 1 and 2), product transportation, business travel, and employee commuting emissions (our scope 3 focus), and to achieve our 100% renewable electricity sourcing goal by the end of 2027;
- epidemics or pandemics, which may negatively impact the global economy in a significant manner for an extended period of time, and could also materially adversely affect our business and operating results;
- industry changes resulting from vertical and horizontal consolidation among our suppliers, competitors, and customers;
- the ability to successfully ramp up new programs that could be impacted by factors beyond our control, including the availability of critical third-party components and performance of subcontractors in line with our expectations; and
- individual customer use of certain products, which may differ from the anticipated uses of such products and result in differences in performance, including energy consumption, may lead to a failure to achieve our disclosed emission-reduction goals, adverse legal action or additional research costs.

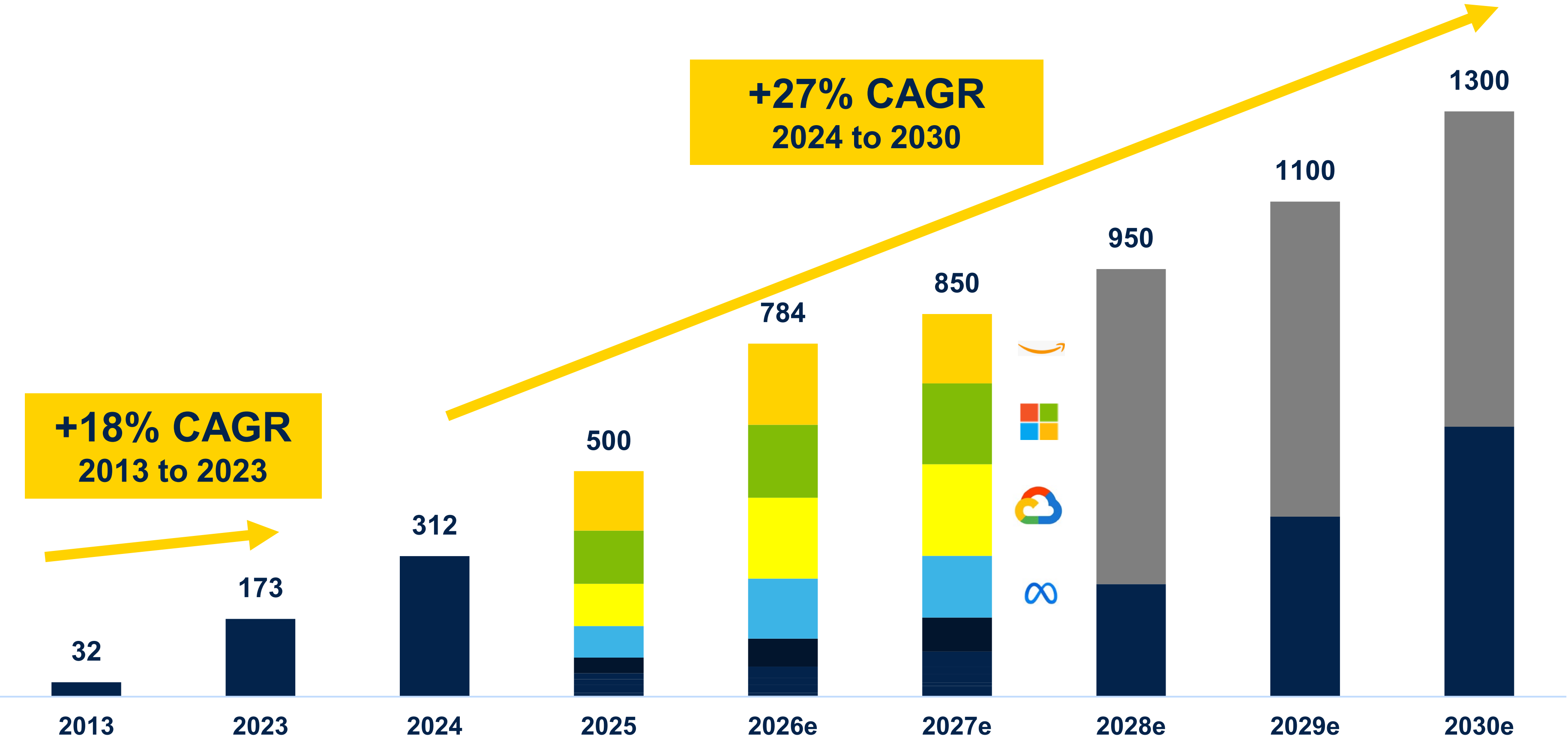
Such forward-looking statements are subject to various risks and uncertainties, which may cause actual results and performance of our business to differ materially and adversely from the forward-looking statements. Certain forward-looking statements can be identified by the use of forward-looking terminology, such as "believes", "expects", "may", "are expected to", "should", "would be", "seeks" or "anticipates" or similar expressions or the negative thereof or other variations thereof or comparable terminology, or by discussions of strategy, plans or intentions.

Some of these risk factors are set forth and are discussed in more detail in "Item 3. Key Information — Risk Factors" included in our Annual Report on Form 20-F for the year ended December 31, 2025 as filed with the Securities and Exchange Commission ("SEC") on February 26, 2026. Should one or more of these risks or uncertainties materialize, or should underlying assumptions prove incorrect, actual results may vary materially from those described in this document as anticipated, believed or expected. We do not intend, and do not assume any obligation, to update any industry information or forward-looking statements set forth in document to reflect subsequent events or circumstances.

Unfavorable changes in the above or other factors listed under "Item 3. Key Information — Risk Factors" from time to time in our SEC filings, could have a material adverse effect on our business and/or financial condition.

Global AI infrastructure expansion: a multi-year Capex catalyst

Hyperscalers Capex spending ($B)



As AI data centers deployments scale, ST is positioned for strong, multi-year growth

Source: Refinitiv, Morgan Stanley Research + UBS estimates by hyperscaler 1Q26 up to 2027, McKinsey, Financial Times/JPMorgan Nov'25 , Dell'Oro Feb'26 up to 2030

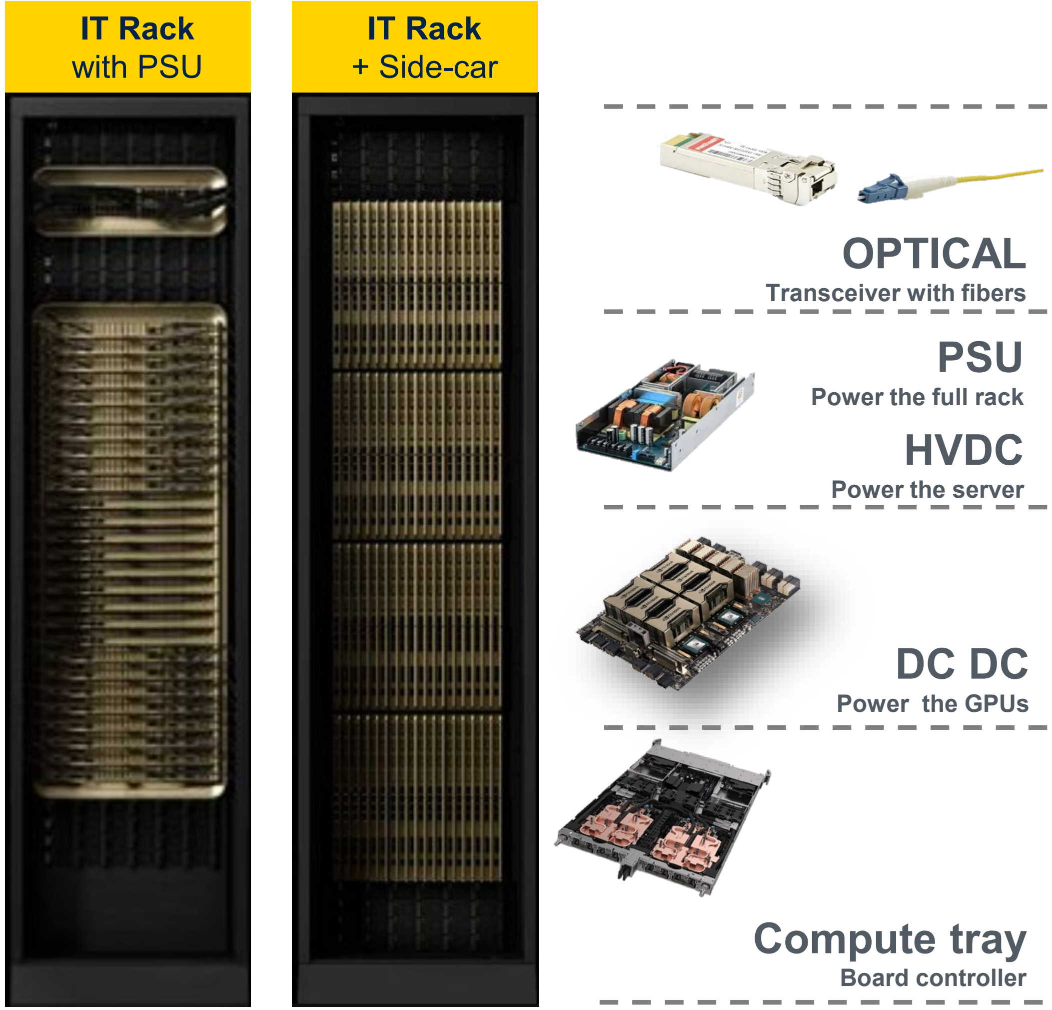
ST SAM Content per 1 GW AI data center

ST SAM $M

~ $230M

For 1GW AI data center

Leveraging a broad AI data center portfolio to accelerate revenue growth.



IT Rack
with PSU

IT Rack
+ Side-car

OPTICAL
Transceiver with fibers

PSU
Power the full rack

HVDC
Power the server

DC DC
Power the GPUs

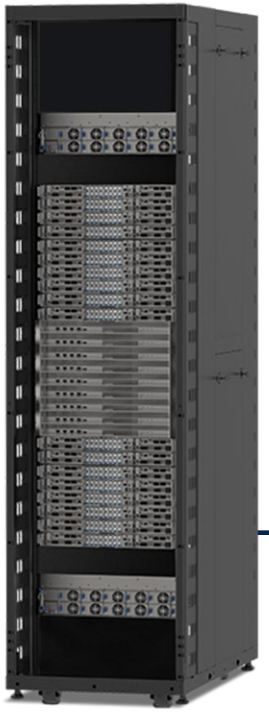
Compute tray
Board controller

Source: Arete, LightCounting, NVIDIA, ST estimates

Power: challenges and architecture (r)evolution

Today – 2025 / 2026

Power: **130 kW – 288 kW**



HV Grid

Low Frequency Transformer

400V AC

server

PSU (AC/DC)

54V

DC/DC

12V

Multiphase Voltage regulator

GPU

Challenges

Growing xPU compute

Size/Space

Conversion Efficiencies/Losses Thermal management

Evolution – 2027 and beyond

Power: **500 kW – 1 MW+**

HV Grid

SST* : High Frequency Transformer + AC/DC

Solid State Circuit Breaker

800V DC

server

DC/DC isolated

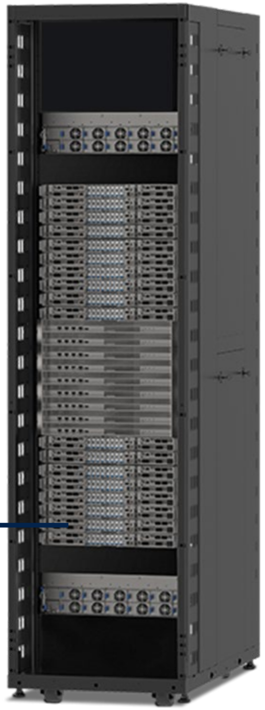
54V / 12V / 6V

DC/DC

12V / 6V / 3.3V / 1.7V

Multiphase Voltage Regulator

GPU



Unlocking 1MW+ rack density through power technologies: Wide bandgap, galvanic isolation and smart power

*SST: Solid State Transformer

ST offering from grid to core power delivery

800V AC-DC

PSU for power shelf applications

High-efficiency and density AC to DC conversion

Based on SiC/GaN for optimized efficiency and power density

8.5-12 kW and beyond capability supporting power shelf configuration

Low profile solution enabling better cooling

800V to 54V

12 kW High density converter

High-efficiency and density 800V DC to DC

Compact, high-power density

GaN MOSFETs enable 1 MHz frequency operation minimizing size of magnetic

Wide range & high output voltage

54V to 12V

2 kW GaN-based “HV Buck”

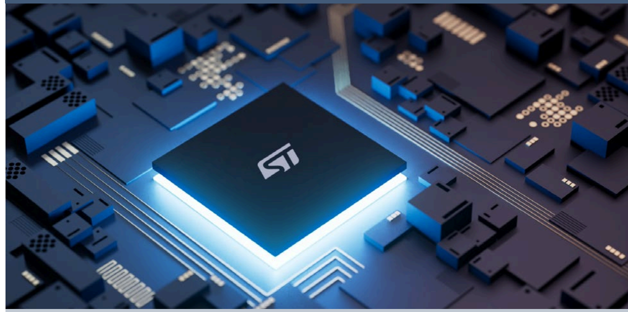
High-efficiency and density intermediate bus converter

Higher power density achieved using GaN devices

Wide input (36-60V) and regulated 12V output

12V to 0.8V

Digital multiphase controller and SPS



STVCOT control loop with SPS

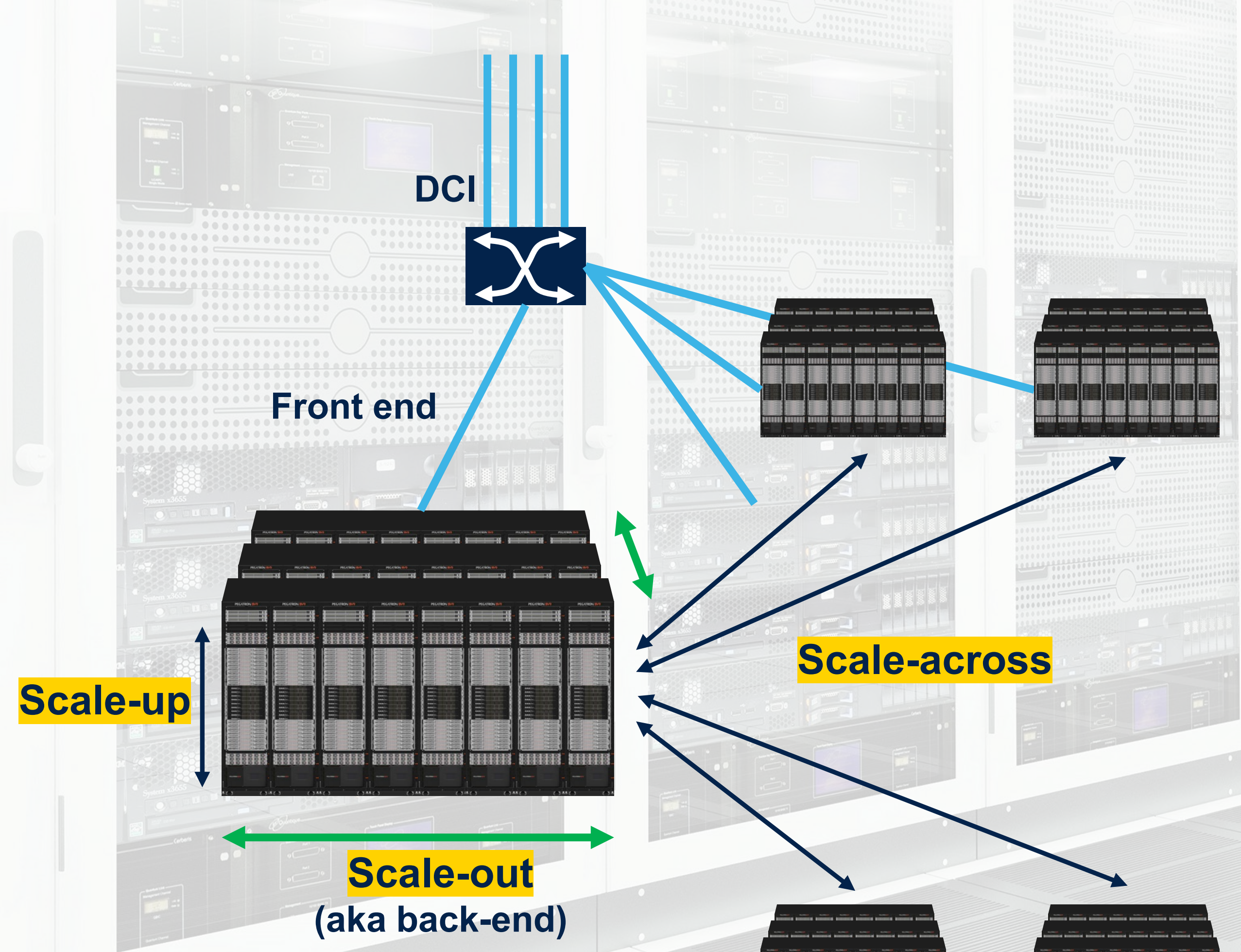
Total solution for 12V to xPU core efficient power delivery

Supporting up to 32 phase VR configuration for high-power xPU

Compliant with Intel, AMD, and Arm®-based CPU

ST covers the complete datacenter power chain, combining SiC, GaN, low-voltage devices, systems in a fully integrated solution

Cloud-optical interconnect in AI servers: Scale-X



Interconnect in an AI data center enables high-speed, reliable, and lossless interaction between compute resources, maximizing efficiency and minimizing job completion time of the AI factory.

A **scale-up** network connects GPUs to switches in a single rack and make them appear as a single compute entity.
Copper today being replaced by optical for compactness

A **scale-out** network (or back-end) connects racks together over medium distances (~km)
Optical fibers used for reach and power consumption

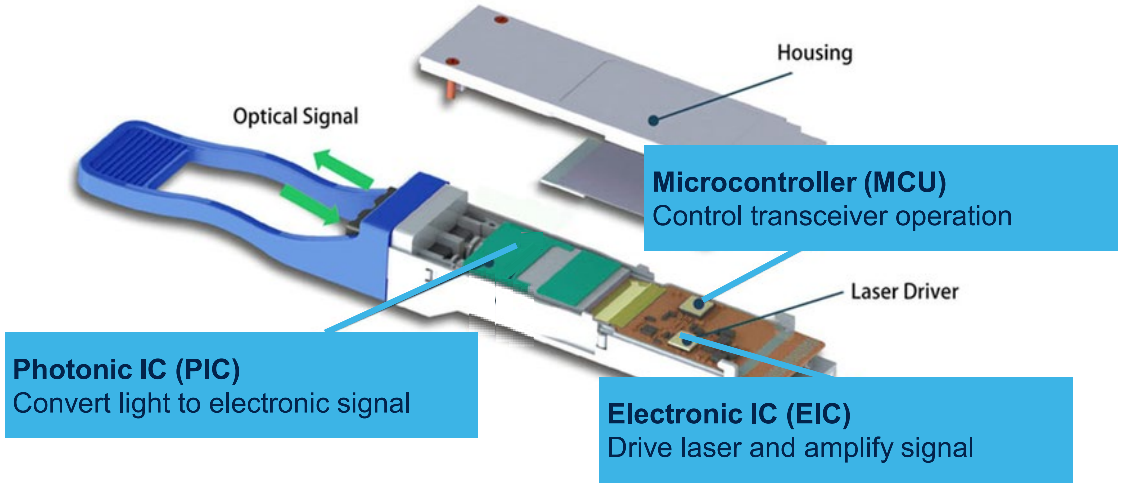
A **scale-across** network connects rack rows together and build bigger AI compute entities
Optical fibers with coherent light for distance & (low) latency

Data Center Interconnect (**DCI**) and front-end connections are covering long distances (>20km) to bring data in
Optical technologies with coherent modulation for far reach

A more detailed view of cloud-optical interconnect products

Pluggable

Courtesy Innolight

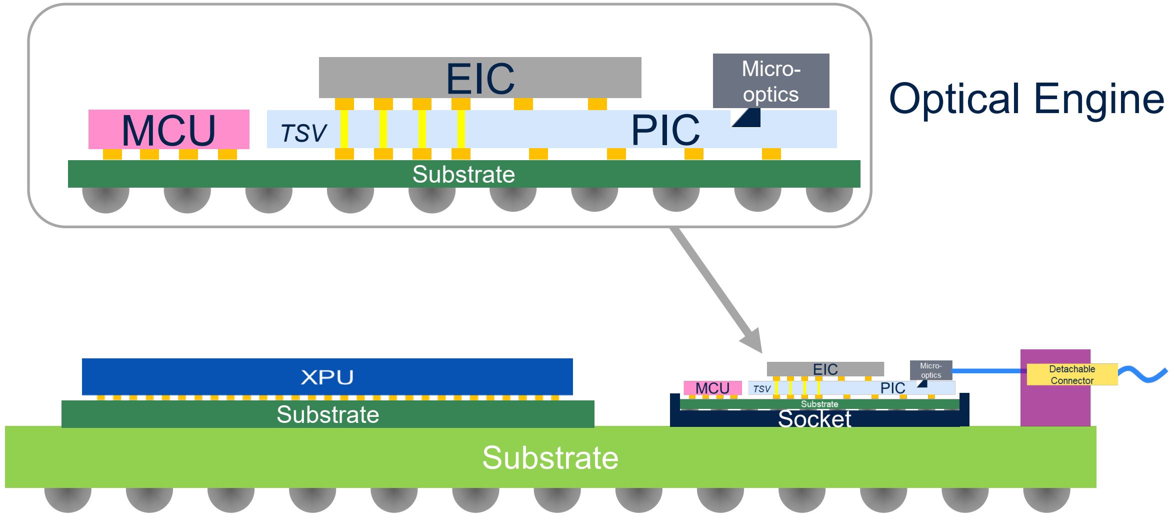


Microcontroller (MCU)
Control transceiver operation

Photonic IC (PIC)
Convert light to electronic signal

Electronic IC (EIC)
Drive laser and amplify signal

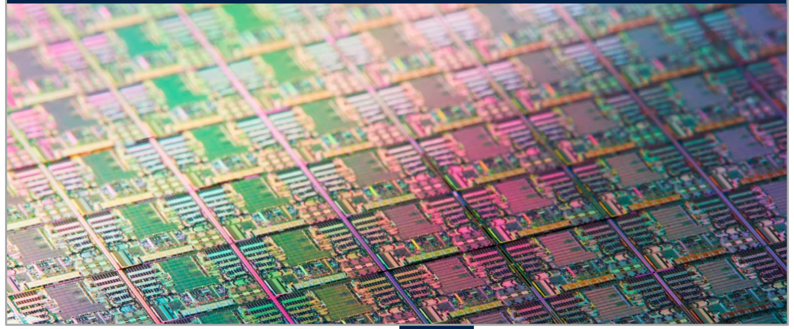
Near-packaged optics (NPO)
Co-packaged optics (CPO)



ST technology integrated in advanced packaging

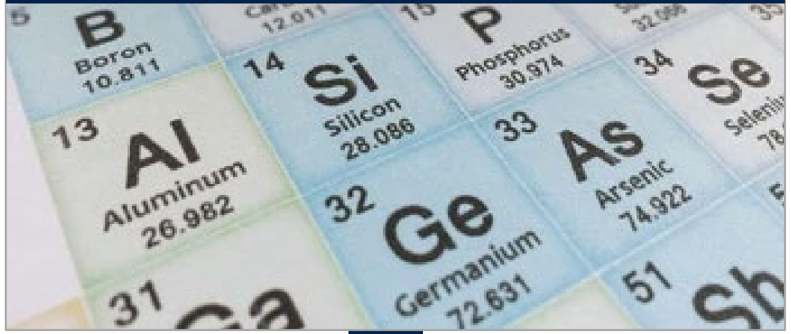
Silicon photonics for PIC

Unique silicon-only 300mm
technology supporting 200G/lane



BiCMOS B55X for EIC

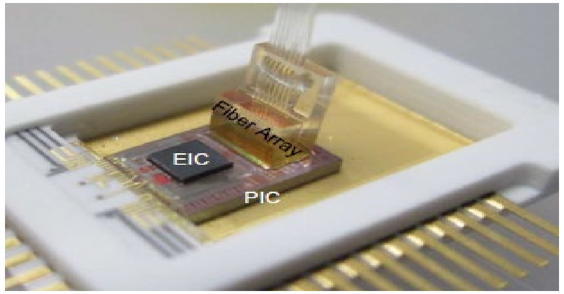
The high-performing 300mm BiCMOS
leading RF & optical markets



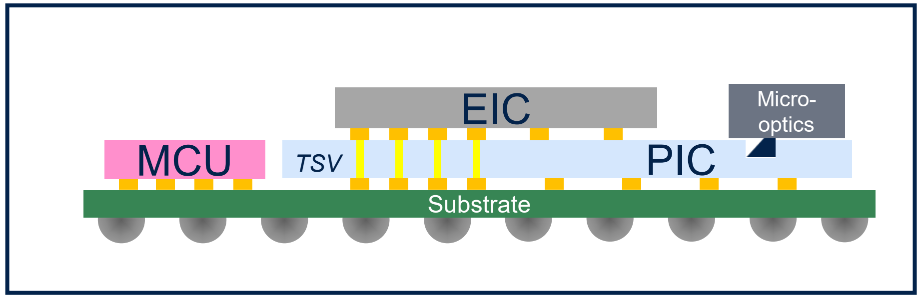
STM32 for MCU

The world's leading
MCU platform

Optical Engine in Advanced Packaging technology



ST provides a codesign environment, dedicated compact modulators, integration support, TSV options, bumping, packaging, and testing for **Optical Engine (OE)**



ST’s industry-leading silicon photonics platform supports AI infrastructure demand

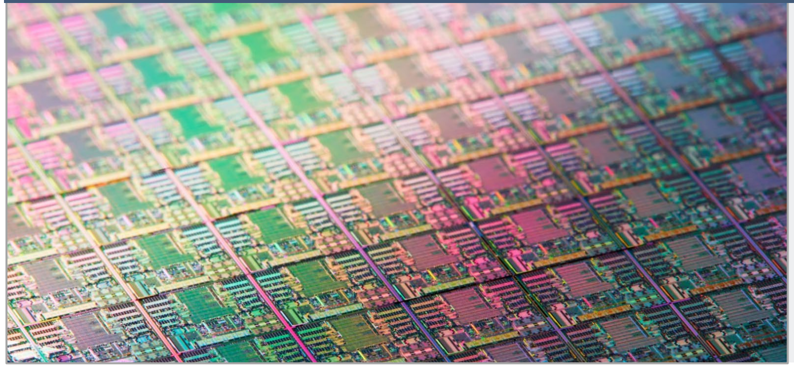
PIC100 in 300mm high-volume production for leading hyperscalers, 4x capacity expansion by 2027

High-volume production for **silicon photonics-based PIC100** platform for optical interconnects for data centers and AI clusters

4x planned capacity expansion by 2027, further expansion in 2028. Fully **underpinned by customers’** long-term capacity reservation commitments

ST provides hyperscalers with **secure, long-term supply, predictable quality, and manufacturing resilience.**

PIC100 TSV platform to support near packaged optics (NPO) and co-packaged optics (CPO)



Next step in silicon photonics roadmap: **PIC100 TSV** to further increase optical connectivity density, module integration, and system-level thermal efficiency

PIC100 TSV is designed for **future generations of near packaged optics (NPO) and co-packaged optics (CPO),** aligning with hyperscalers’ long-term migration paths toward deeper optical–electronic integration for scale up

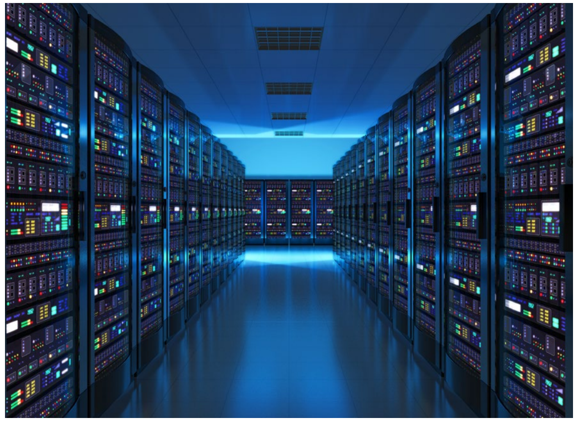
Strategic collaboration with AWS

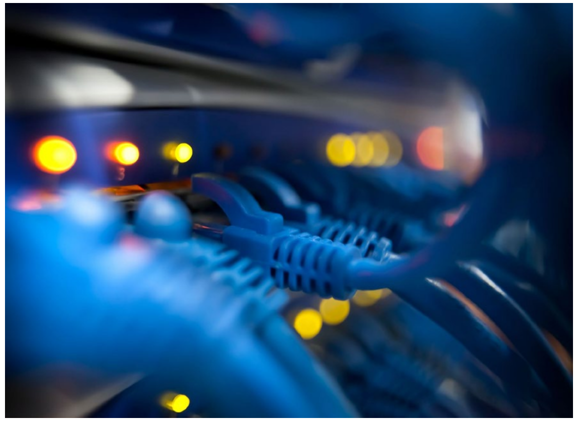
Multi-year, multi-billion $ commercial engagement with AWS serving several product categories

A major milestone to position ST in the AI revolution.

This collaboration establishes ST as a strategic supplier of advanced semiconductor technologies and products that AWS integrates into its compute infrastructure.

ST will supply specialized capabilities across high-bandwidth connectivity, including high-performance mixed-signal processing, advanced MCUs for intelligent infrastructure management, and analog and power ICs.



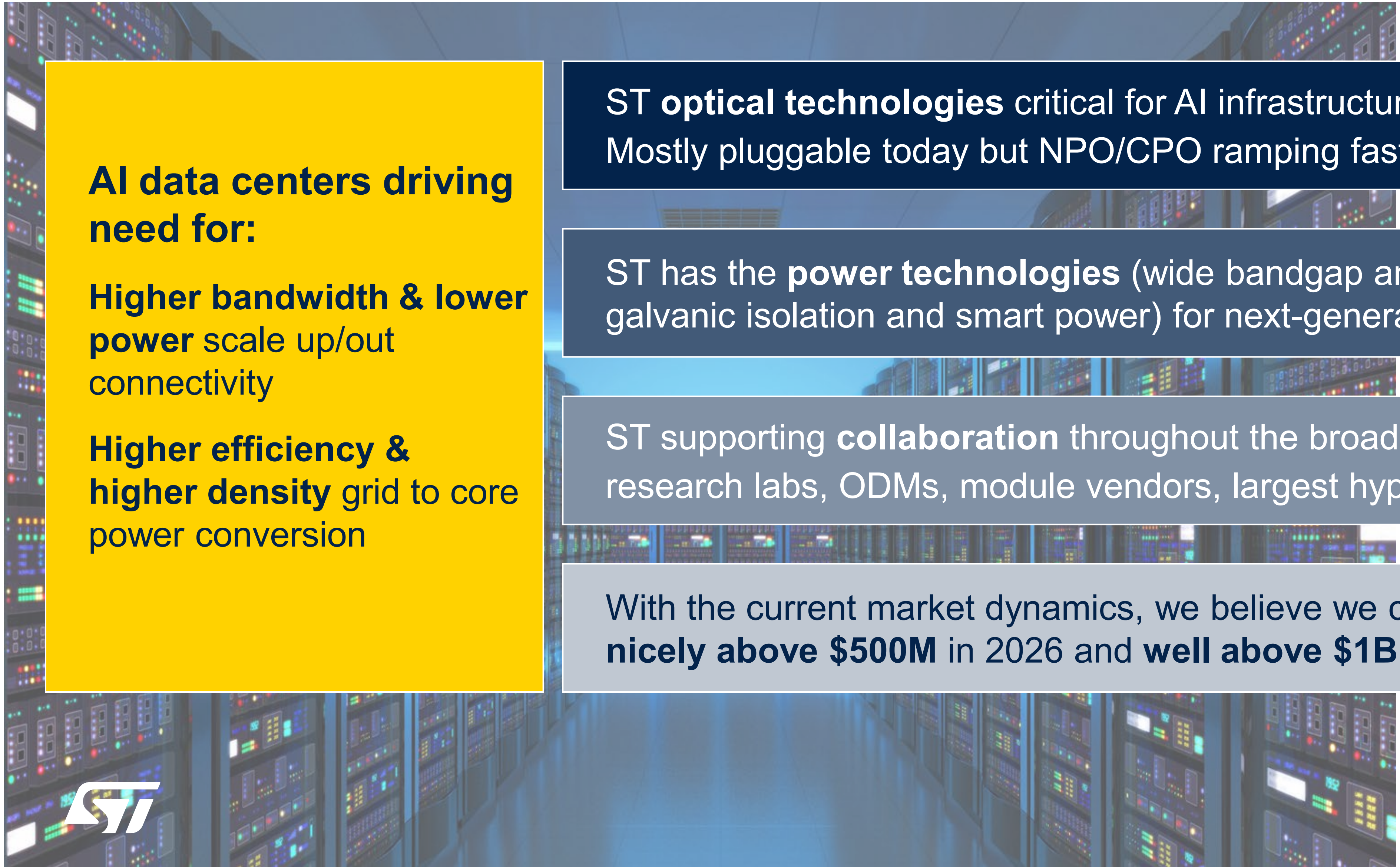


ST AI data center revenue growth expected to further accelerate

With the current market dynamics, we believe we can achieve revenue nicely above **$500 million** in **2026**.

And we believe we can achieve revenue well above $**1 billion in 2027**.

Takeaways



AI data centers driving need for:

Higher bandwidth & lower power scale up/out connectivity

Higher efficiency & higher density grid to core power conversion

ST **optical technologies** critical for AI infrastructure
Mostly pluggable today but NPO/CPO ramping fast

ST has the **power technologies** (wide bandgap and silicon based, galvanic isolation and smart power) for next-generation AI data centers

ST supporting **collaboration** throughout the broad ecosystem
research labs, ODMs, module vendors, largest hyperscalers

With the current market dynamics, we believe we can achieve **revenue nicely above $500M** in 2026 and **well above $1B** in 2027.

Our technology starts with You

Find out more at www.st.com